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(21) International Application Number: PCT/US96/09705 (22) International Filing Date: 7 June 1996 (07.06.96) (30) Priority Data: 08/474,929 7 June 1995 (07.06.95) US (71) Applicant: THE DEXTER CORPORATION [US/US]; 2850 Willow Pass Road, Pittsburg, CA 94565 (US). (72) Inventors: GEBHARDT, William, F.; 639 Odin Drive, Pleasant Hill, CA 94523 (US). PAPALIA, Rocco; 3331 Blue Jay Drive, Antioch, CA 94509 (US). (74) Agents: BRUHN, David, E. et al.; Dorsey & Whitney L.L.P., Pillsbury Center South, 220 South Sixth Street, Minneapolis, MN 55402-1498 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BB, BG, BR, BY, CA, CH, CN, CZ, DE, DK, EE, ES, FI, GB, GE, HU, IS, JP, KE, KG, KP, KR, KZ, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, TJ, TM, TR, TT, UA, UG, UZ, VN, ARIPO patent (KE, LS, MW, SD, SZ, UG), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>
(54) Title: CONDUCTIVE FILM COMPOSITE		
(57) Abstract A thin film printed board precursor containing a laminate of a dielectric thermosetting resin film layer (6) and a heat and electrically conductive metal foil layer (5) in direct adhesive bonding with a side of the resin film (6), optionally containing a supporting layer (22) comprising one or more of fiber, fabric and thermoplastic polymer in contact with the other side of the resin layer (6), wherein the dielectric thermosetting resin layer (6) has an unimpeded thickness that is at least equal to that of the foil layer (5) bonded to it.		